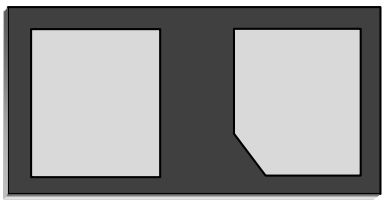
Etek Microelectronics

ES03DMSBHX

Transient Voltage Suppressor

Features

- 120 Watts Peak Pulse Power per Line (tp = 8/20μs)
- Small Body Outline Dimensions
- Protects one I/O or Power Line
- Low Clamping Voltage
- Working Voltage: 3.3V
- Low Leakage Current



DFN0603-2L

IEC Compatibility (EN61000-4)

- IEC 61000-4-2 (ESD) ±30kV (air), ±30kV (contact)
- IEC 61000-4-4 (EFT) 40A (5/50ns)
- IEC 61000-4-5 (Lightning) 12A (8/20μs)

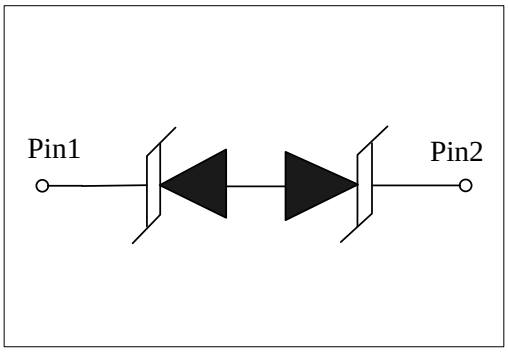
Mechanical Characteristics

- DFN0603-2L package
- Marking : Marking Code
- Packaging: Tape and Reel per EIA 481
- RoHS Compliant
- MSL1

Applications

- Laptop Computers
- Cellular Phones
- Digital Cameras
- Personal Digital Assistants (PDAs)

Schematic & PIN Configuration

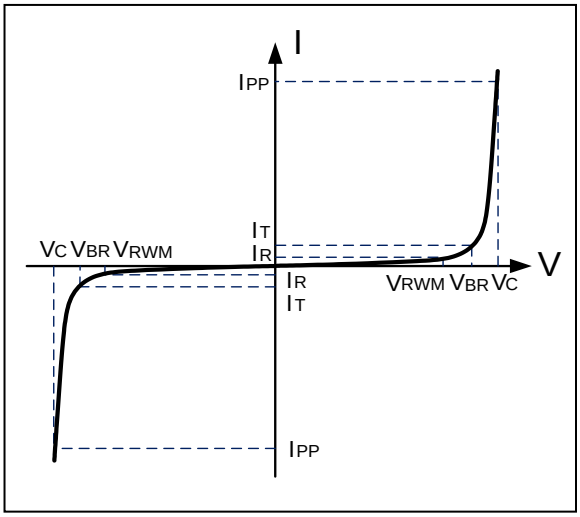


Absolute Maximum Rating

Rating	Symbol	Value	Units
Peak Pulse Power (t_p = 8/20μs)	P_{PP}	120	W
Peak Pulse Current (t_p = 8/20μs)	I_{PP}	12	A
Operating Temperature	T_J	-55 to + 125	℃
Storage Temperature	T_{STG}	-55 to +150	℃

Electrical Parameters (T=25℃)

Symbol	Parameter
I_{PP}	Reverse Peak Pulse Current
V_C	Clamping Voltage @ I_{PP}
V_{RWM}	Reverse Stand-Off Voltage
I_R	Reverse Leakage Current @ V_{RWM}
V_{BR}	Breakdown Voltage @ I_T
I_T	Test Current



Electrical Characteristics

Parameter	Symbol	Conditions	Min	Typ	Max	Units
Reverse Stand-Off Voltage	V_{RWM}				3.3	V
Reverse Breakdown Voltage	V_{BR}	I_T=1mA	4.5			V
Reverse Leakage Current	I_R	V_{RWM}=3.3V, T=25℃			100	nA
Clamping Voltage	V_C	I_{PP}=12A, t_p=8/20μs		8	10	V
Dynamic Resistance[1,2]	R_{DYN}	TLP=0.2/100ns		0.2		Ω
ESD Clamping Voltage[1]	V_C	I_{PP} = 4A, t_p = 0.2/100ns (TLP)		5.5		V
ESD Clamping Voltage[1]	V_C	I_{PP} = 16A, t_p = 0.2/100ns (TLP)		7.4		V
Junction Capacitance	C_j	V_R =0V, f =1MHz		22	30	pF

Notes：1、TLP Setting：t_p=100ns, t_r=0.2ns, I_{TLP} and V_{TLP} sample window:t_1=70ns to t_2=90ns.
2、Dynamic resistance calculated from I_{PP}=4A to I_{PP}=16A using “Best Fit”.

Typical Characteristics

Figure 1: Peak Pulse Power Vs Pulse Time

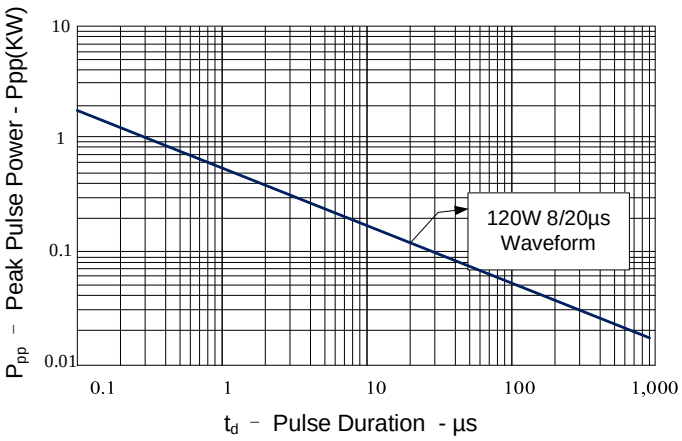


Figure 2: Power Derating Curve

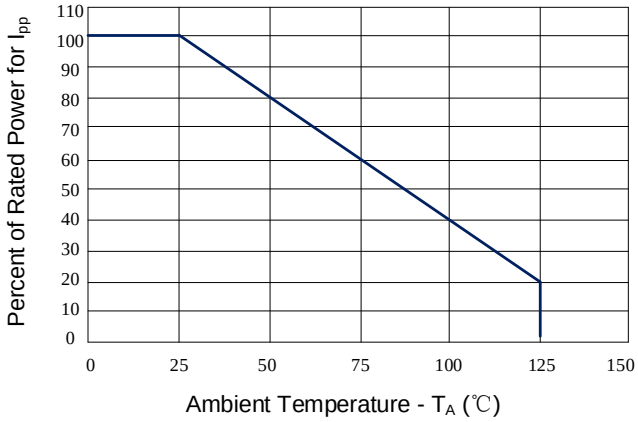


Figure 3: Clamping Voltage vs. Peak Pulse Current

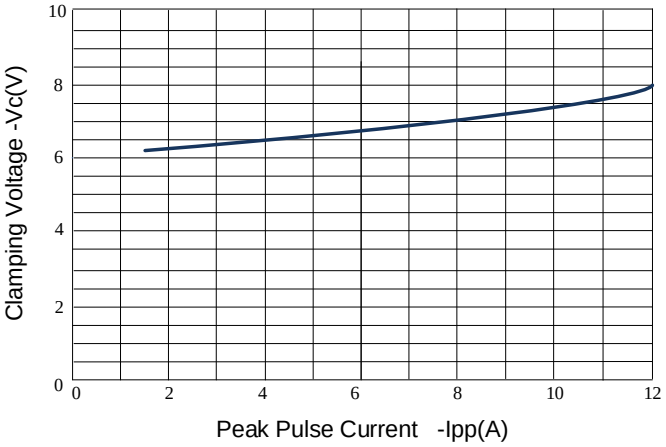


Figure 4: Normalized Junction Capacitance vs. Reverse Voltage

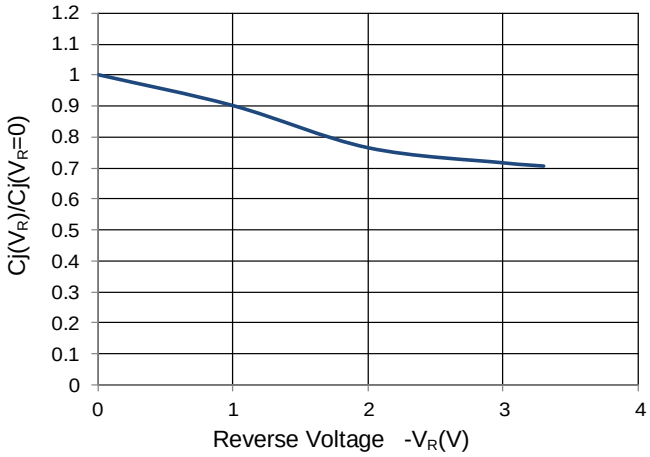


Figure 5: TLP Positive I-V Curve

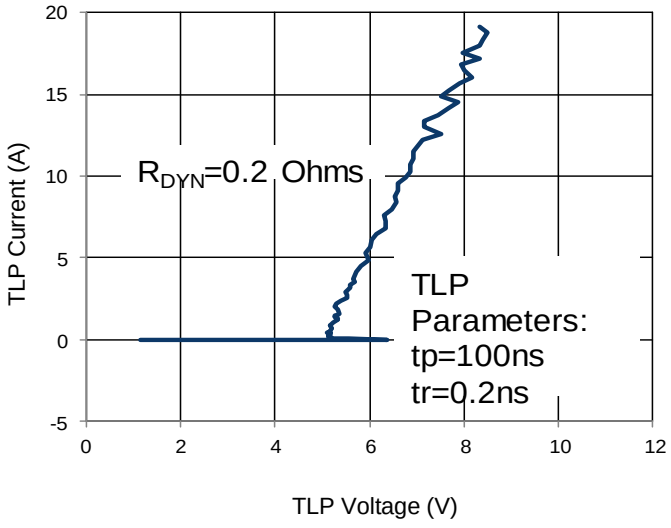
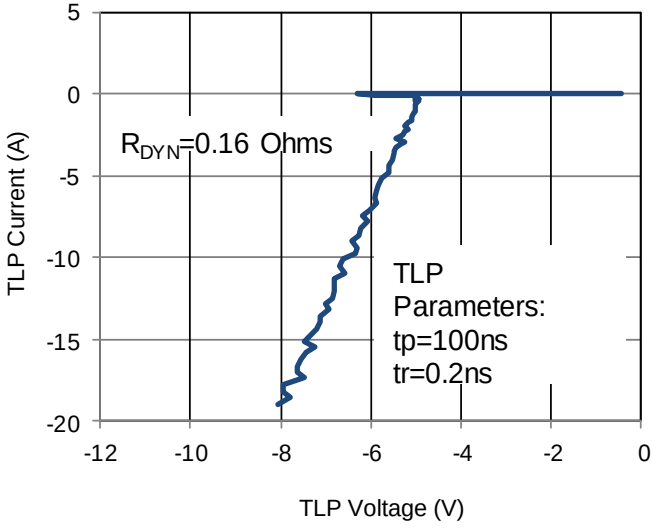
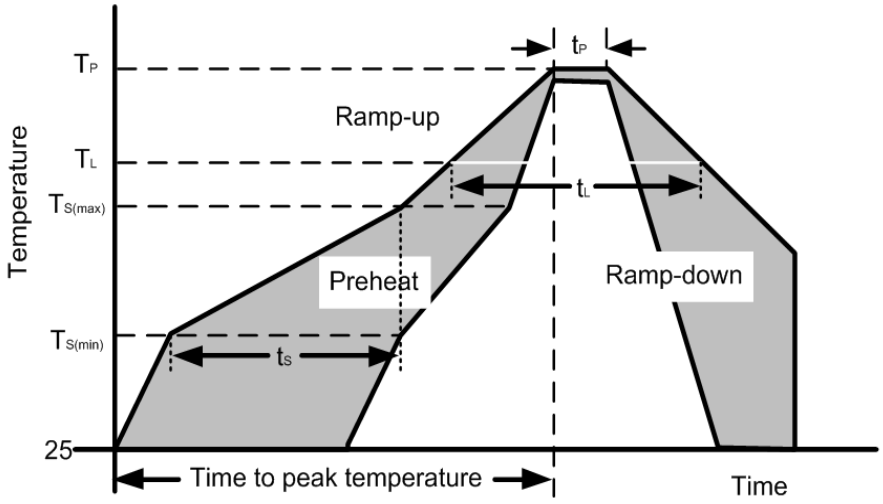


Figure 6: TLP Negative I-V Curve



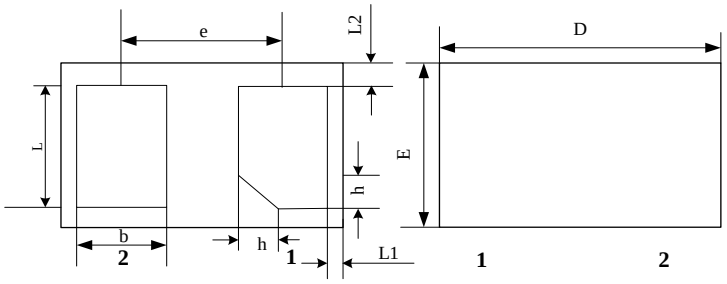
Soldering Parameters

Parameter		Value
Reflow Condition		Pb – Free assembly
Pre Heat	Temperature Min (Ts(min))	150°C
	Temperature Max (Ts(max))	200°C
	Time (min to max) (Ts)	60 ~190 secs
Average ramp up rate (Liquidus Temp) (T_L) to peak		5°C/second max
Ts(max) to T_L——Ramp-up Rate		5°C/second max
Reflow	Temperature (T_L) (Liquidus)	217°C
	Temperature (T_L)	60 ~150 seconds
Peak Temperature (T_P)		260+0/-5 °C
Time within actual peak Temperature (T_P)		20 ~ 40 seconds
Ramp-down Rate		5°C/second max
Time 25°C to peak Temperature (T_P)		8 minutes Max.
Do not exceed		280°C

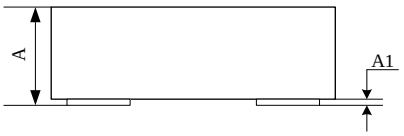


Outline Drawing –DFN0603-2L

PACKAGE OUTLINE



Bottom View Top View

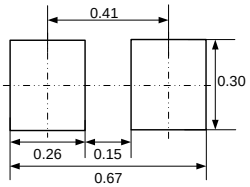


Side View

DFN0603-2L

SYMBOL	MILLIMETERS		
	NOM	MIN	MAX
A	--	0.280	0.320
A1	--	--	0.050
D	0.620	0.570	0.640
E	0.320	0.270	0.340
b	0.180	0.155	0.205
L	0.240	0.200	0.265
h	--	0.050	0.100
L1	0.040REF		
L2	0.040REF		
e	0.360BSC		

Land Pattern



Marking Codes

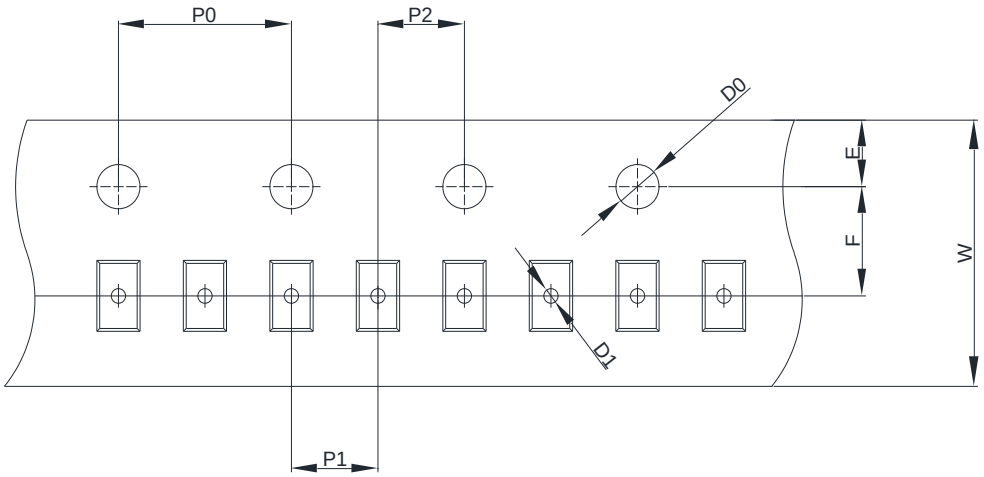
Part Number	Marking Code
ES03DMSBHX	1 B≧ 2 B=Specific Device Code M=Month Code

Package Information

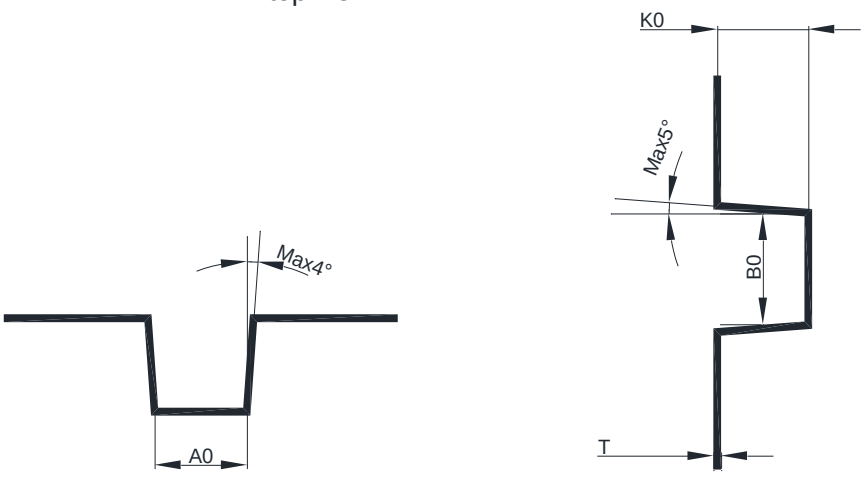
Qty：15k/Reel

Tape Information

Tape Dimensions



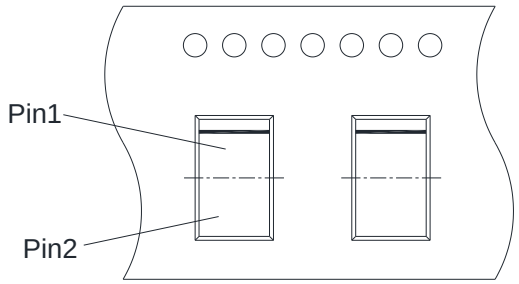
top view



front view

end view

Quadrant Assignments For PIN1 Orientation In Tape



User Direction of Feed

SYMBOL	A0	B0	K0	P0	P1	P2
SPEC	0.38±0.03	0.68±0.03	0.34±0.03	4.00±0.10	2.00±0.05	2.00±0.05
SYMBOL	T	E	F	D0	D1	W
SPEC	0.18±0.05	1.75±0.10	3.50±0.05	1.55±0.05	0.20±0.05	8.00±0.1

Revision History

No.	Version	Date	Revision Item	Request	Function and characteristic checking	Package dimension checking	Typos checking
1	1.0	2020-08-12	Released Version	Qi Shu Kun	Yin Peng	Ge Zheng Bing	Liu Jia Ying
2	1.1	2022-02-16	Update Tape Information	Qi Shu Kun	Qi Shu Kun	Liu Jia Ying	Liu Jia Ying